

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hiroshi Maeda, et al.

Serial No.: 10/633,576

Filed: August 05, 2003



Customer Number: 20277

Confirmation Number: 5440

Group Art Unit: 2811

Examiner: To be Assigned

For: SEMICONDUCTOR DEVICE WITH CAPACITOR ELECTRODES AND METHOD OF
MANUFACTURING THEREOF

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop IDS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Information Disclosure Statement and 1449 Form is supplemental to that filed August 5, 2003. The reason for this supplemental Information Disclosure Statement and 1449 Form is to correct a typographical error made on the initial 1449 Form.. The last listed Prior Art Publication was initially filed with a typographical error in the title. The title should be changed to read: "Copper Dual Damascene Wiring....." as indicated on attached copies.

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

MCDERMOTT, WILL & EMERY

 A handwritten signature in black ink, appearing to read "Stephen A. Becker".

Stephen A. Becker
Registration No. 26,527

600 13th Street, N.W.
Washington, DC 20005-3096
(202) 756-8000 SAB:mcw
Facsimile: (202) 756-8087
Date: November 13, 2003

INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)			ATTY. DOCKET NO. 57454-963	SERIAL NO. Divisional of Serial No. 09/903,735		
			APPLICANT Hirosi MAEDA, ET AL.			
			FILING DATE August 5, 2003	GROUP To be assigned		
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	6,424,011	07/2002	Assaderaghi et al	257	350	
	6,255,151	07/2001	Fukuda et al	257	296	
FOREIGN PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation
						Yes
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)						
	M. Igarashi, A. Harada, H. Amishiro, H. Kawashima, N. Morimoto, Y. Kusumi, T. Saito, A. Ohsaki, T. Mori, T. Fukada, Y. Toyoda, K. Higashitani, and H. Arima, "The Best Combination Of Aluminum and Copper Interconnects For a High Performance 0.18 μ m CMOS Logic Device," IEDM98, 1998, PP. 829-832.					
	J. Heidenreich, D. Edelstein, R. Goldblatt, W. Cote, C. Uzoh, N. Lustig, T. McDevitt, A. Stamper, A. Simon, J. Dukovic, R. Wachnik, H. Rathore, S. Luce, and J. Slattery, "Copper Dual <u>Damascene</u> Wiring for Sub-0.25 μ m CMOS Technology," PP. 13-15.					
EXAMINER	DATE CONSIDERED					

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.